APE Asia Photonics Expo

What Can the Semiconductor Industry Visitors Explore at APE?

4-6 February 2026
Sands Expo and Convention Centre (Marina Bay Sands) L1

*Based on the exhibit profile of APE 2026, listed in no order.

Semiconductor Supporting Industry

Semiconductor Material

- Silicon Wafer
- Electronic Specialty Gas
- Specialty Glass
- Photoresist
- Photomask
- Polishing Material
- Wet Electronic Chemical
- Sputtering Target
- Packaging Substrate
- Lead Frame
- Bonding Gold Wire
- Dicing Material
- Ceramic Packaging Material
- Glass Substrate

Wafer Manufacturing Equipment

- Oxidation Furnace
- Annealing Equipment
- Coater/Developer
- Lithography System
- Etching System
- Stripping System
- Ion Implanter
- CVD Equipment
- PVD Equipment
- ALD Equipment
- Direct Writing System
- Cleaning Equipment
- Polishing Equipment
- Automatic Wafer Defect Detection System
- Dimensional Metrology Platform
- High-Precision Optical Measurement System

Packaging & Testing Equipment

- Wafer Thinner
- Wafer Dicer
- Laser Dicing Machine
- Semiconductor Die Bonder
- Wire Bonder
- Flip Chip Bonder
- Sorter
- Electron Microscope
- Optical Microscope
- Probe Station
- Tester
- Wire Bonding Machine
- Molding System
- X-ray Inspection System

Third-Generation Semiconductor

- Aluminum Nitride
- GaN Epitaxial Wafer
- SiC Epitaxial Wafer
- GaN Wafer
- SiC Substrate
- SiC Polishing Slurries
- SiC Mirror
- SiC Epitaxial CVD System
- SiC Structural Component
- SiC Laser Equipment
- SiC Epitaxial Equipment
- GaN Epitaxial Equipment

Core Components & Subsystems for Semiconductor Equipment

Key Component

- Precision Motion Stage
- Quartz Component
- Structural Part
- Industrial Sensor
- Sealing Ring
- Precision Bearing
- Controller
- RF Generator
- Mass Flow Controller
- Gas Flow Meter
- Vacuum Pump
- Valves & Valve Core
- Coating Material
- Electrostatic Chuck
- Robotic Arm
- Transmission System

Optical System

- Optical Lens
- Optical Component
- Laser Light Source
- Lens System
- Mirror

Wafer Foundry/Fabrication

- Wafer Fabrication/Foundry
- OSAT Provider

Sign-up for emails

Semiconductor Industry

Design/Chips & Application

- EDA/IP
- Communication Chip
- Memory Chip
- CPU Chip
- Sensor Chip
- Analog Chip
- Digital Chip
- DSP Chip
- RF Chip
- Driver Chip

Discrete Device

- Diode
- High-Frequency Diode
- Transistor
- MOSFET
- IGBT

Sensor

- MEMS Sensor
- Visual Perception Sensor
- Visual Sensor Chip
- LiDAR
- Imaging Sensor
- Distance Sensor
- Displacement Sensor
- Fiber Optic Sensor
- Infrared Thermopile Array Sensor

Optoelectronic Device

- Laser Chip
- Detector Chip
- Passive Optoelectronic Chip
- Photodiode
- Photodetector
- Optical Controller
- LED
- Semiconductor Laser
- Photomultiplier Tube
- Optical Module
- Optical Display Device
- Optical Amplifier